

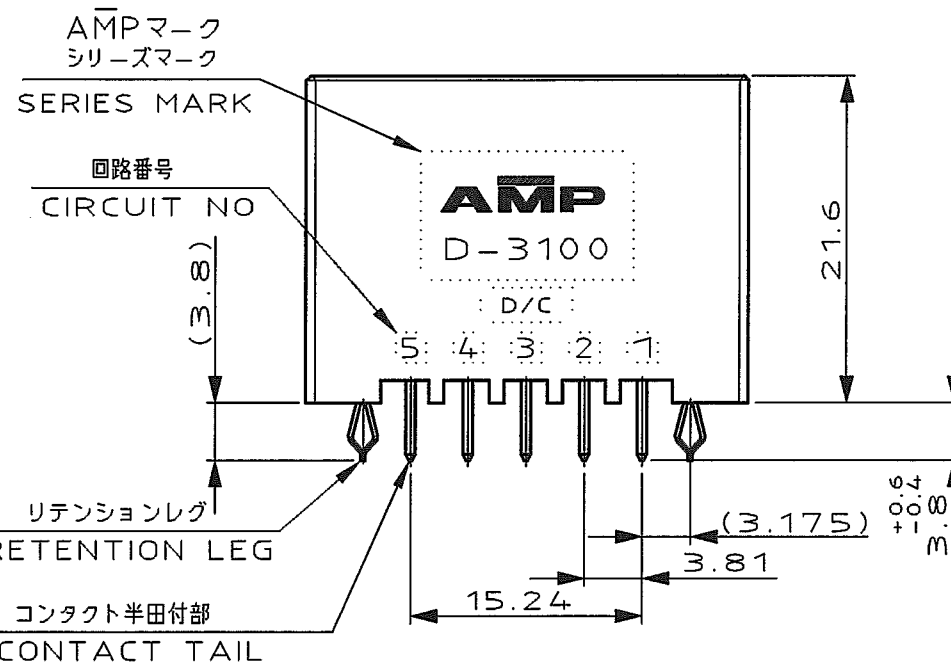
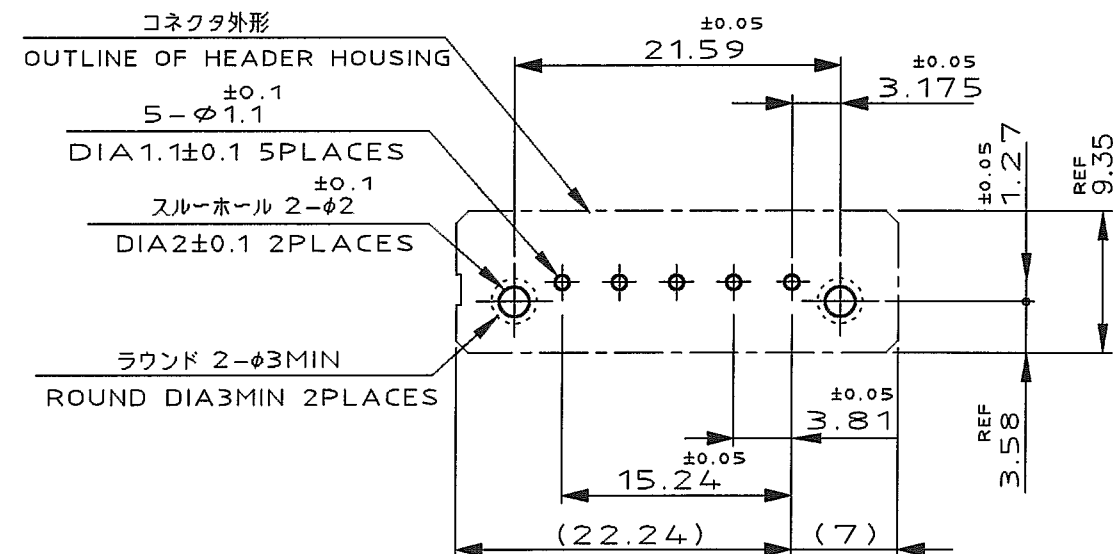
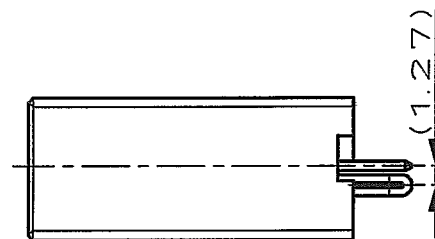
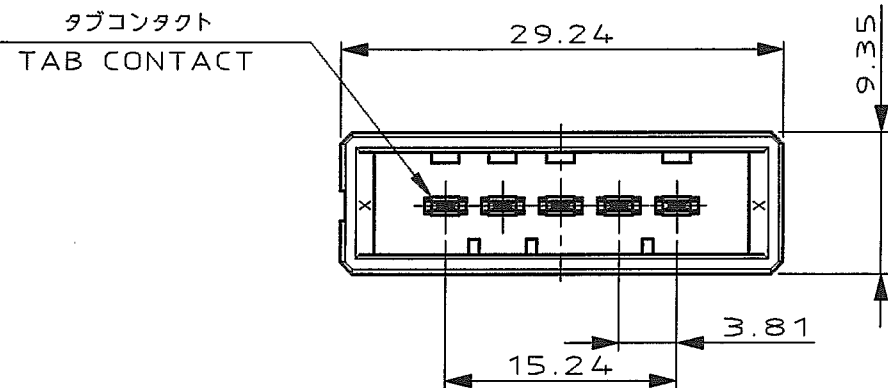
NUMBER 178315



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J
REV.10/83

推奨基板取付け寸法

PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性
ポリエステル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

6	4	1-178315-5
6	3	1-178315-3
6	2	1-178315-2
(FINISH)		製品番号 (PART NO.)

E	REVISED	FJD0-0039-03	TS	SM	6/2/93
D	REVISED	FJD0-0114-03	TS	SM	25 APR '03
C	REVISED	FJ00-2744-95	KI	S.M	16 JUN '95
B	REVISED	FJ00-0838-94	NM	S.M	7/4 '94
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM	S.M	4/20 '94
LTR	REVISION RECORD		DR	CHK	DATE

Copyright © 1994 AMP(Japan) LTD. ALL RIGHTS RESERVED.		tyco Electronics		Tyco Electronics AMP K.K. Kawasaki, Japan	
WIRE RANGE		INSULATION DIA		NAME	
mm (AWG)		mm		5 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC D-3100	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 19 APR 94 N. Matsubara		DE. 19 APR 94 N. Matsubara		SIZE LOC NUMBER A3 J C=178315	
CHK. 20 APR 94 S. MANABE		APP. 20 APR 94 S. MANABE		SCALE REV. SHEET 2-1 E 1 OF 1	

(CUSTOMER DRAWING) 顧客用図面